

### **REMARKS**

Claim 1 has been amended by adding the subject matter of claim 7 thereto and claims 7 to 9 have been canceled. Claims 1 to 5 remain active in this application.

Claim 7, which is essentially present claim 1, was rejected under 35 U.S.C. 103(a) as being unpatentable over Terada et al. (U.S. 5,874,773) in view of Arago, College Physics and Parker et al. (6,087,842). The rejection is respectfully traversed.

Claim 1 now requires a chip mount pad having at least one slit penetrating the whole thickness of the pad and substantially traversing the area of the pad from one edge to the opposite edge, the slit wide enough to interrupt electron flow in the pad plane, but not wide enough to significantly reduce thermal conduction in a direction normal to the pad plane, whereby the slit is operable to disrupt eddy currents induced in the pad by the changing magnetic field, the device further including a chip having an integrated circuit including a Hall device. No such structure is taught or suggested by the applied references taken alone or in any proper combination.

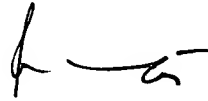
While Terada et al. teaches a leadframe having slits therein, nowhere does Terada et al. mention or even remotely suggest any relation of the leadframe therein to minimization of eddy currents, though it is agreed that such action could take place in Terada et al. Parker et al. teaches a Hall device in an integrated circuit, but nowhere teaches or suggests the combination with a leadframe having slits to minimize eddy currents. It follows that though the elements of the claimed combination exist in the prior art, nowhere except in the subject disclosure is there a recognition of the advantages of combining the leadframe having slits with an eddy current device. It follows that the combination of references is a result of a prior reading of the subject disclosure since the

prior art nowhere teaches or even remotely suggests the combination of elements as claimed.

Claims 2 to 5 depend from claim 1 and are therefore patentable for at least the reasons presented above with reference to claim 1.

In view of the above remarks, favorable reconsideration and allowance are respectfully requested.

Respectfully submitted,

A handwritten signature in black ink, appearing to read "Jay M. Cantor", with a stylized flourish at the end.

Jay M. Cantor  
Attorney for Applicant(s)  
Reg. No. 19,906

Texas Instruments Incorporated  
P. O. Box 655474, MS 3999  
Dallas, Texas 75265  
(301) 424-0355 (Phone)  
(972) 917-5293 (Phone)  
(301) 279-0038 (Fax)